

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1921is8#trpbf

(Engineering Calculation)

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**TOTAL MASS (g) : 0.07332**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001980	1000000	27004.9628906		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.014071	580000	191912.546875		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.010189	420000	138966.453125		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.024260</b>	<b>1000000</b>	<b>330879</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001477	1000000	20142.59375		
		<b>External Plating Total:</b>				<b>0.001477</b>	<b>1000000</b>	<b>20142.59375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000194	1000000	2645.94067383		
<b>Internal Plating Total:</b>				<b>0.000194</b>	<b>1000000</b>	<b>2645.94067383</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000690	750000	9410.82128906		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000230	250000	3136.94018555		
<b>Die Attach Total:</b>				<b>0.000920</b>	<b>1000000</b>	<b>12547.7607422</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004571	103000	62343.28125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.039720	895000	541735.9375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000089	2000	1213.85949707		
		<b>Encapsulation Total:</b>				<b>0.044380</b>	<b>1000000</b>	<b>605293.125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000109	1000000	1486.63696289		
					<b>TOTAL MASS (g) :</b>	<b>0.07332</b>		